

## Zytel<sup>®</sup> HTN54G35HSLR NC010 HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTN54G35HSLR NC010 is a 35% glass reinforced, toughened, heat stabilised high performance polyamide resin. It is also a PPA resin.

#### **Product information**

Resin Identification Part Marking Code Part Marking Code ISO designation	PA-IGF35 >PA-IGF35< >PPA-IGF35< ISO 16396-PA-I,GF35,M1GHNRW,S10-100		ISO 1043 ISO 11469 SAE J1344
Rheological properties	dry/cond.		
Viscosity number	105/*	cm³/g	ISO 307, 1628
Moulding shrinkage, parallel	0.2/-	%	ISO 294-4, 2577
Moulding shrinkage, normal	0.6/-	%	ISO 294-4, 2577
Typical mechanical properties	dry/cond.		
Tensile modulus	10000/-	MPa	ISO 527-1/-2
Tensile stress at break, 5mm/min	180/-	MPa	ISO 527-1/-2
Tensile strain at break, 5mm/min	3/-	%	ISO 527-1/-2
Flexural modulus	9000/-	MPa	ISO 178
Tensile creep modulus, 1h	*/11000	MPa	ISO 899-1
Tensile creep modulus, 1000h	*/10000	MPa	ISO 899-1
Charpy impact strength, 23°C	75/-	kJ/m <sup>2</sup>	ISO 179/1eU
Charpy notched impact strength, 23°C	12/11	kJ/m <sup>2</sup>	ISO 179/1eA
Charpy notched impact strength, -40°C	9/-	kJ/m²	ISO 179/1eA
Poisson's ratio	0.34/-		
Thermal properties	dry/cond.		
Melting temperature, 10°C/min	304/*	°C	ISO 11357-1/-3
Glass transition temperature, 10°C/min	120/65	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	255/*	°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	285/*	°C	ISO 75-1/-2
Coeff. of linear therm. expansion, parallel, -40-23°C	20/*	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	20/*	E-6/K	ISO 11359-1/-2
Coeff. of linear therm. expansion, normal, -40-23°C	75/*	E-6/K	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE),	72/*	E-6/K	ISO 11359-1/-2
normal			· · · · · · · · ·
Thermal conductivity, flow	0.35	W/(m K)	ISO 22007-2



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Flammability			
FMVSS Class	SE		ISO 3795 (FMVSS 302)
Electrical properties	dry/cond.		
Surface resistivity	*/1E14	Ohm kV/mm	IEC 62631-3-2
Electric strength Comparative tracking index	43/42 600/-	KV/IIIII	IEC 60243-1 IEC 60112
Physical/Other properties	dry/cond.		
Humidity absorption, 2mm	1.8/*	%	Sim. to ISO 62
Density	1420/-	kg/m³	ISO 1183
Injection			
Drying Recommended	ye		
Drying Temperature Drying Time, Dehumidified Dryer	100 °C 6-8 h		
Processing Moisture Content		1 %	
Melt Temperature Optimum		5 °C	
Min. melt temperature Max. melt temperature		0°C 0°C	
Min. mould temperature	90	O°C	
Max. mould temperature	130	O°C	
Characteristics			
Processing	Injection Moulding		
Delivery form	Pellets		
Additives	Release agent		
Special characteristics	Heat stabilised or stable to heat, Hydrolysis resistant		
Additional information			
Injection molding	During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the holdup time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.		
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### Automotive

OEM	STANDARD
Bosch	N28 BN05-OX089
Ford	WSS-M98P14-A3
General Motors	GMW18066P-PPA-GF35
Hyundai	MS211-80 Type B

ADDITIONAL INFORMATION

Natural

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